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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
AMENDMENT TRANSMITTAL LETTER

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as first class mail in an envelope addressed to Commissioner of Patents and Trademarks, Washington, D.C. 20231 on January 22, 2002.

Elizabeth A. Jue
Elizabeth A. Jue

RECEIVED
FEB 22 2002
TECHNOLOGY CENTER 2800

Applicant : Rong-Fuh Shyu
Application No. : 09/383,150
Filed : August 25, 1999
Title : LEAD FRAME FOR A SEMICONDUCTOR CHIP PACKAGE, SEMI CONDUCTOR CHIP PACKAGE INCORPORATING MULTIPLE INTEGRATED CIRCUIT CHIPS, AND METHOD OF FABRICATING...
Grp./Div. : 2826
Examiner : F. Abraham
Docket No. : 35761/DBP/S295

Assistant Commissioner for Patents
Washington, D.C. 20231

Post Office Box 7068
Pasadena, CA 91109-7068
January 22, 2002

Enclosed is an amendment to the above-identified application.

| CLAIMS AS AMENDED | | | | | | |
|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------------------------------------------|-------------------------------|---------------------------|----------------------|----------------------|-----|
| | Claims Remaining After Amendment | Highest Number Paid For | Number Extra Claims | Small Entity Rate | Large Entity Rate | FEE |
| Total Claims Fee | 8 | * 20 | 0 | x \$9.00 | x \$18.00 | |
| Independent Claims | 2 | ** 3 | 0 | x \$42.00 | x \$84.00 | |
| Multiple Dependent Claims *** | | | | \$140.00 | \$280.00 | |
| TOTAL FILING FEE | | | | | | \$0 |
| NO ADDITIONAL FEE REQUIRED **** | IF NO FEE REQUIRED, INSERT "0" | | | | | 0 |
| LIST INDEPENDENT CLAIMS: 1, 4 | | | | | | |
| * IF HIGHEST NUMBER PREVIOUSLY PAID FOR IS 20 OR LESS, WRITE "20" IN COLUMN 3 ** IF HIGHEST NUMBER PREVIOUSLY PAID FOR IS 3 OR LESS, WRITE "3" IN COLUMN 3 *** PAY THIS FEE ONLY WHEN MULTIPLE DEPENDENT CLAIMS ARE ADDED FOR THE FIRST TIME **** IF NO FEE REQUIRED, ADDRESS ENVELOPE TO "BOX NON-FEE AMENDMENTS" | | | | | | |

- ___ Attached is our check for \$ to pay the fees calculated above.
- ___ A Petition for Extension of Time and the required fee are enclosed.

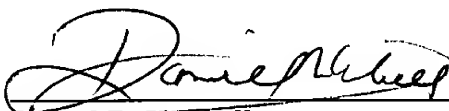
Amendment Transmittal Letter
Application No. 09/383,150

X Other enclosures: Return Postcard

The Commissioner is hereby authorized to charge any fees under 37 CFR 1.16 and 1.17 which may be required by or to give effect to this paper to Deposit Account No. 03-1728. Please show our docket number with any charge or credit to our Deposit Account. **A copy of this letter is enclosed.**

Respectfully submitted,

CHRISTIE, PARKER & HALE, LLP

By 

Daniel R. Kimbell

Reg. No. 34,849

626/795-9900

DRK/eaj

#13/A (N.E.)

2-25-02

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FEB 22 2002

RESPONSE UNDER 37 CFR 1.116
EXPEDITED PROCEDURE
EXAMINING GROUP 2826

TECHNOLOGY CENTER 2800
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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AMENDMENT AFTER FINAL ACTION

 Box AF
Assistant Commissioner for Patents
Washington, D.C. 20231


Post Office Box 7068
Pasadena, CA 91109-7068
January 22, 2002

Commissioner:

In response to the Final Action of October 22, 2001, please amend the above-identified application as follows:

In the Claims

Please amend claims 1 and 4 as follows:

-  1. (Amended) A lead frame for a completed and assembled semiconductor chip package, said lead frame comprising:
- a unitary frame body;
 - at least two chip-receiving windows formed in said unitary frame body, each of said chip-receiving windows being adapted to receive a respective integrated circuit chip therein;